

APPLICATION DATA SHEET**Inventor Information**

Inventor One Given Name	:	Sion C.
Family Name	:	QUINLAN
Postal Address Line One	:	1, Lockstile Way
Postal Address Line Two	:	Goring on Thames
City	:	Oxon
Postal or Zip Code	:	RG8
Country of Residence	:	United Kingdom
Citizenship Country	:	United Kingdom

Inventor Two Given Name	:	Tim J.
Family Name	:	BALES
Postal Address Line One	:	15 Derbyshire Green
Postal Address Line Two	:	Warfield
City	:	Bracknell
Postal or Zip Code	:	RG42 -3TG
Country of Residence	:	United Kingdom
Citizenship Country	:	United Kingdom

Correspondence Information

Name Line One	:	Steven H. Arterberry, Esq.
Address Line One	:	DORSEY & WHITNEY LLP
Address Line Two	:	1420 Fifth Avenue, Suite 3400
City	:	Seattle
State or Province	:	Washington
Postal or Zip Code	:	98101
Telephone	:	206-903-8800
Facsimile	:	206-903-8820
E-Mail	:	patentseattle@dorsey.com

Application Information

Title	:	SEMICONDUCTOR PACKAGE ASSEMBLY AND METHOD FOR ELECTRICALLY ISOLATING MODULES
Total Drawing Sheets	:	3
Formal Drawings	:	YES
Application Type	:	Utility
Attorney Docket Number	:	30022/US/3
Assigned	:	Yes (Large Entity)

Representative Information

Representative Customer No. : 27,076

Continuity Information

This application is a : divisional of
>Application One : 10/057,205
Filing Date : January 25, 2002

Prior Foreign Application

Foreign Application One : 0126821.8
Filing Date : November 7, 2001
Country : United Kingdom
Priority Claimed : Yes

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